PART INFORMATION

Mfg Item Number	MPC8560CPX667JC
Mfg Item Name	FCPBGA 783 29SQ*3.9P1.0

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2012-05-11
Response Document ID	5301K10807D025A1.18
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	No
Pb Free	No
HalogenFree	Yes
Plating Indicator	e0
EU RoHS Exemption(s)	15

MANUFACTURING

Mfg Item Number	MPC8560CPX667JC
Mfg Item Name	FCPBGA 783 29SQ*3.9P1.0
Version	ALL
Weight	4.617700
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2002/95/EC
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	2 - Item(s) contain RoHS restricted substances above the limits and is not under exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemptions in this part	
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight
	6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight
	6(c) : Copper alloy containing up to 4% lead by weight
	7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
	7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
	7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
	7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
	7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC
	7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
	15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

SubPart	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	REACHPPM	REACH%
Underfill	0.0439						g				
Underfill		Solvents, additives, and other materials	Methylhexahydrophthalic anhydride	25550-51-0		0.006632	g	151065	15.1065	1436	0.1436
Underfill		Plastics/polymers	1,3-bis(2,3-epoxypropoxy)-2,2-dimethylpropane	17557-23-2		0.002445	g	55695	5.5695	529	0.0529
Underfill		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27610-48-6		0.002445	g	55695	5.5695	529	0.0529
Underfill		Plastics/polymers	Elastomer Modified Diglycidyl Ether	68909-14-8		0.002445	g	55695	5.5695	529	0.0529
Underfill		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.028657	g	652781	65.2781	6205	0.6205
Underfill		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.001276	g	29069	2.9069	276	0.0276
Solder Balls - Low Lead	0.4743						g				
Solder Balls - Low Lead		Metals	Lead, metallic lead and lead alloys	7439-92-1		0.170748	g	360000	36	36976	3.6976
Solder Balls - Low Lead		Metals	Silver, metal	7440-22-4		0.009486	g	20000	2	2054	0.2054
Solder Balls - Low Lead		Metals	Tin, metal	7440-31-5		0.294066	g	620000	62	63683	6.3683
Bonding Agent	0.0368						g				
Bonding Agent		Metals	Aluminum, metal	7429-90-5		0.03128	g	850000	85	6773	0.6773
Bonding Agent		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.00552	g	150000	15	1195	0.1195
Cap/Cover	1.4686						g				
Cap/Cover		Metals	Cadmium, metal	7440-43-9		0.000004	g	3	0.0003	0	0
Cap/Cover		Metals	Chromium phosphate(III)	59178-46-0		0.000004	g	3	0.0003	0	0
Cap/Cover		Metals	Copper, metal	7440-50-8		1.442333	g	982113	98.2113	312359	31.2359
Cap/Cover		Metals	Lead, metallic lead and lead alloys	7439-92-1		0.000004	g	3	0.0003	0	0
Cap/Cover		Metals	Magnesium, metal	7439-95-4		0.002019	g	1375	0.1375	437	0.0437
Cap/Cover		Metals	Mercury	7439-97-6		0.000004	g	3	0.0003	0	0
Cap/Cover		Metals	Nickel, metal	7440-02-0		0.024232	g	16500	1.65	5247	0.5247
Capacitor, 0306	0.0408						g				
Capacitor, 0306		Metals	Copper, metal	7440-50-8		0.00563	g	138000	13.8	1219	0.1219
Capacitor, 0306		Metals	Nickel, metal	7440-02-0		0.007956	g	195000	19.5	1722	0.1722
Capacitor, 0306		Metals	Tin, metal	7440-31-5		0.00053	g	13000	1.3	114	0.0114
Capacitor, 0306		Metals	Barium titanate	12047-27-7		0.026684	g	654000	65.4	5778	0.5778
Capacitor Solder Paste	0.0026						g				
Capacitor Solder Paste		Metals	Copper, metal	7440-50-8		0.000013	g	5000	0.5	2	0.0002
Capacitor Solder Paste		Metals	Lead, metallic lead and lead alloys	7439-92-1		0	g	83	0.0083	0	0
Capacitor Solder Paste		Metals	Silver, metal	7440-22-4		0.000078	g	30000	3	16	0.0016
Capacitor Solder Paste		Metals	Tin, metal	7440-31-5		0.002509	g	964917	96.4917	543	0.0543
Organic Substrate, Halogen-fre	2.3291				15		g				
Organic Substrate, Halogen-fre		Metals	Copper, metal	7440-50-8		0.9378	g	402645	40.2645	203092	20.3092
Organic Substrate, Halogen-fre		Plastics/polymers	Other Epoxy resins	-		0.678197	g	291184	29.1184	146872	14.6872
Organic Substrate, Halogen-fre		Metals	Lead, metallic lead and lead alloys	7439-92-1		0.000887	g	381	0.0381	192	0.0192
Organic Substrate, Halogen-fre		Glass	Fiberglass	-		0.619753	g	266091	26.6091	134214	13.4214
Organic Substrate, Halogen-fre		Glass	Other silica compounds	-		0.07526	g	32313	3.2313	16298	1.6298
Organic Substrate, Halogen-fre		Metals	Silver, metal	7440-22-4		0.01673	g	7183	0.7183	3623	0.3623
Organic Substrate, Halogen-fre		Metals	Tin, metal	7440-31-5		0.000473	g	203	0.0203	102	0.0102
High Pb Bumped Semiconductor D	0.2216				15		g				
High Pb Bumped Semiconductor D		Metals	Lead, metallic lead and lead alloys	7439-92-1		0.02087	g	94177	9.4177	4519	0.4519
High Pb Bumped Semiconductor D		Metals	Nickel, metal	7440-02-0		0.000183	g	825	0.0825	39	0.0039
High Pb Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.001098	g	4956	0.4956	237	0.0237
High Pb Bumped Semiconductor D		Metals	Titanium, metal	7440-32-6		0.000009	g	42	0.0042	1	0.0001
High Pb Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.001994	g	9000	0.9	431	0.0431
High Pb Bumped Semiconductor D		Glass	Silicon, doped	-		0.197446	g	891000	89.1	42758	4.2758

LINKS	
MCD LINK	
Freescale website	http://www.freescale.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf
China RoHS	http://www.freescale.com/chinarohs
REACH signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf
ELV signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf
Conflict Minerals statement	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf
FREESCALE ENVIRONMENTAL INFORMATION	
EPP website	http://www.freescale.com/epp
FAQ	http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ
Technical Service Request	https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v0.9 Form	http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v0.9_MCD_Template.pdf
Blank IPC1752 v1.1 Form	http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPC8560CPX667JC_IPC1752_v09.xml

http://www.freescale.com/mcds/MPC8560CPX667JC_IPC1752_v11.xml

http://www.freescale.com/mcds/MPC8560CPX667JC_IPC1752A.xml